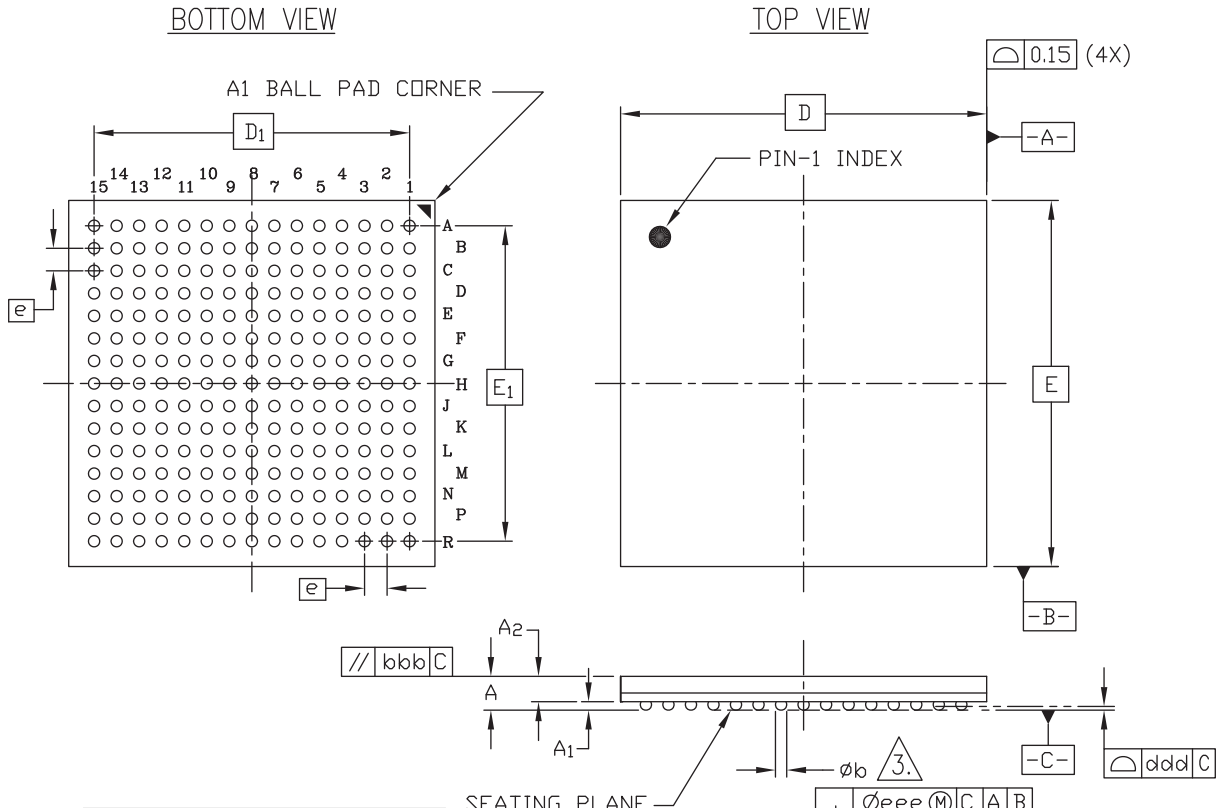


225 Ball Chip-Scale BGA (CS225/CSG225) Package, 0.80 mm Pitch



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	1.00	\approx	1.40	3.0
A ₁	0.25	0.30	0.40	
A ₂	0.75	0.90	1.00	
$\frac{D}{E}$	13.00 BSC			
$\frac{D_1}{E_1}$	11.20 BSC			
$\frac{e}{e}$	0.80 BSC			
ϕb	0.35	0.40	0.45	
bbb	\approx	\approx	0.20	
ddd	\approx	\approx	0.10	
eee	\approx	\approx	0.15	
fff	\approx	\approx	0.08	
M	15			2

CS225 - 63/37 Sn/Pb SOLDER BALLS
 CSG225 - Sn/4.0Ag/0.5Cu SOLDER BALLS

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
- SYMBOL "M" IS THE PIN MATRIX SIZE.
- 3.0 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- THERE SHALL BE A MINIMUM CLEARANCE OF 0.25mm BETWEEN THE EDGE OF THE SOLDER BALL AND THE BODY EDGE.
- CONFORMS TO JEDEC MO-275-HHAC-1.

PK380_01_111209

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
11/23/09	1.1	Changed the orientation of the A1 ball pad corner indicator.

Notice of Disclaimer

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